2nd World Congress on ARTIFICIAL INTELLIGENCE IN ATERIALS & MANUFACTURING 2024

TMSSPECIALTY CONGRESS 2024

JUNE 16-20, 2024 Cleveland Hilton Cleveland, Ohio, USA

REGISTER NOW

The TMS World Congress on Artificial Intelligence in Materials and Manufacturing (AIM 2024) is the second event of its kind to focus on the role of artificial intelligence (AI) in materials science and engineering and related manufacturing processes. AIM 2024 will convene stakeholders from academia, industry, and government to address key issues and future pathways.

AIM 2024 will include the following specific technical topics:

- Al Application to Non-Destructive Evaluation (NDE & Data)
- Bridging Length Scales (from Laboratory to Manufacturing)
- · Data Management: Curation, Collection, and Verification
- High-Throughput Synthesis & Characterization
- Image Processing
- Large Language Models (LLMs) for Materials
- Machine Learning Algorithm Development for Materials Science
- Machine Learning/Deep Learning applied to Manufacturing Process Optimization
- Machine Learning/Deep Learning applied to Discovery of Materials
- Robotics & Automation

Congress participants are encouraged to submit their work to the TMS journal *Integrating Materials and Manufacturing Innovation*, which will be publishing a topical collection dedicated to this event. This collection will take the place of a traditional conference proceedings publication. Only submissions from participants will be considered for this collection. Submissions will go through the journal's standard peer review process, and there is no guarantee of acceptance. The journal submission deadline is August 31, 2024.

ORGANIZERS

LEAD ORGANIZER:

 Adam Kopper, Mercury Marine

ORGANIZING COMMITTEE:

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